Multi Line AOI for SMD

AOI system for SMD PCBAs

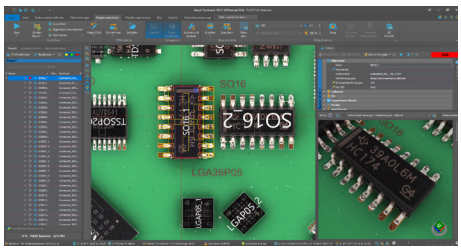
- cost-effective 3D AOI system for inline use
- configurable for double-sided, simultaneous inspection
- fully automatic AOI test program generation with MagicClick in a few minutes
- flexible data interfaces for line communication as well as for MES and traceability
- can be used as a full 3D SPI system



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Technical specifications

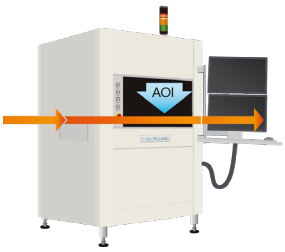
Parameters	Data
camera module	3D AOI
image capturing	3D/2D camera module with orthogonal camera, telecentric optics and 3D image capturing sensors
resolution per pixel	15 µm
max. inspection height	35 mm
component clearance	40 mm
possible uses in Multi Line	component and solder joint inspection from above and below
Multi Line platform	
max. inspection area	540 mm x 450 mm
max. carrier size	up to 620 mm x 510 mm
max. transport weight	15 kg
energy requirement	230 VAC / 2 kVA, compressed air 6 bar, consumption < 20 l/h
transport system	conveyor belt for PCBAs with or without carriers
transport direction	left-right, right-left, left-left, right-right
inline interface	SMEMA, HERMES, Siemens, Sensor
dimensions (w x d x h)	1150 mm x 1300 mm x 1800 mm
weight	approx. 800 kg



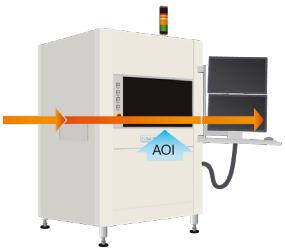
Multi Line software



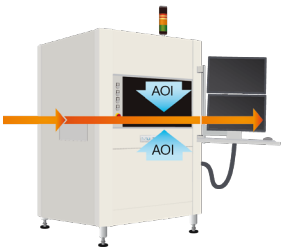
Configuration variants



Inspection from above



Inspection from below



Inspection on both sides

IPC-HERMES-9852
The global standard for "M2M" in SMT assembly

IPC CFX

GÖPEL electronic

ISO 9001 certified

GÖPEL electronic GmbH
Goeschwitzer Str. 58/60
07745 Jena · Germany

+49 3641 · 6896 0 Phone
+49 3641 · 6896 944 Fax

inspection.sales@goepel.com
www.goepel.com

USA inspection.sales@goepelusa.com **India** inspection.sales@goepel.in